

#### SUBMINIATURE SOLID STATE LAMP

AM27ID09

HIGH EFFICIENCY RED

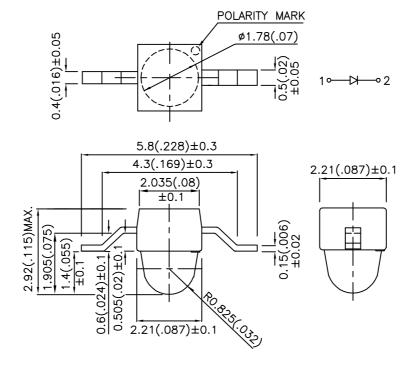
#### **Features**

- SUBMINIATURE PACKAGE.
- •WIDE VIEWING ANGLE.
- •Z-BEND LEAD.
- •LONG LIFE SOLID STATE RELIABILITY.
- •LOW PACKAGE PROFILE.
- •PACKAGE:1000PCS/REEL.
- •Rohs Compliant.

### **Description**

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

### **Package Dimensions**



#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

SPEC NO: DSAD1324 APPROVED: J. Lu REV NO: V.4 CHECKED: Allen Liu DATE: MAR/05/2005 DRAWN: W.J.ZHU PAGE: 1 OF 4 ERP:1202000265

# Kingbright

### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min. Typ.		201/2
AM27ID09	HIGH EFFICIENCY RED (GaAsP/GaP)	RED DIFFUSED	7	30	40°

Note:

## Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD	Dominant Wavelength	High Efficiency Red	625		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF	Forward Voltage	High Efficiency Red	2.0	2.5	V	IF=20mA
IR	Reverse Current	High Efficiency Red		10	uA	VR = 5V

## Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units	
Power dissipation	105	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		

Note

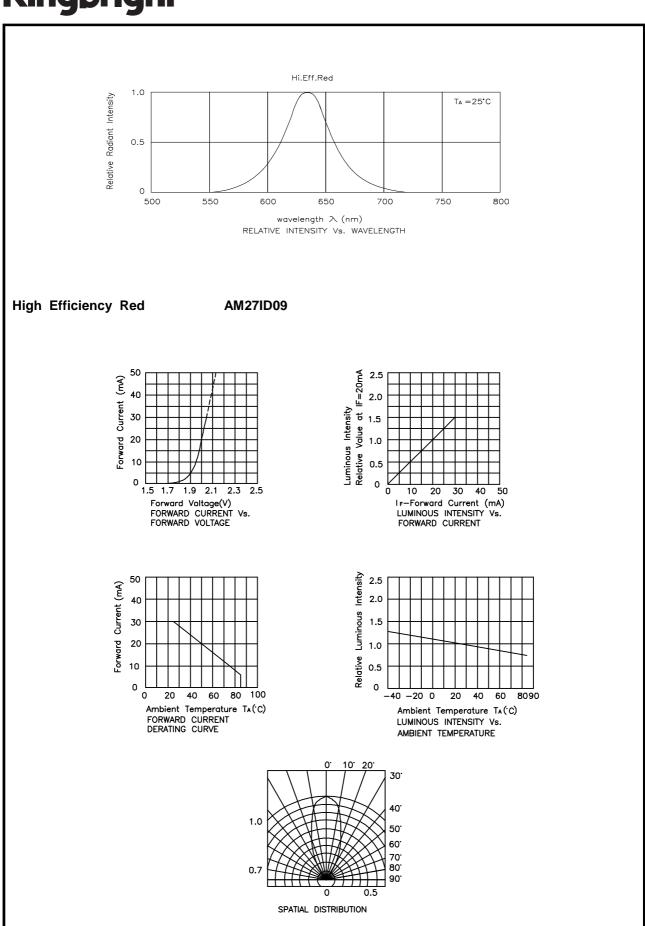
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<sup>1.</sup>  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

<sup>1. 1/10</sup> Duty Cycle, 0.1ms Pulse Width.

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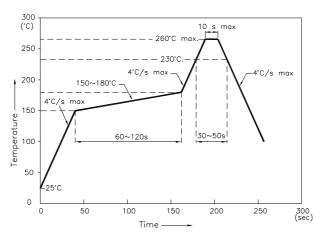


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#### **AM27ID09**

Reflow Soldering Profile For Lead-free SMT Process.

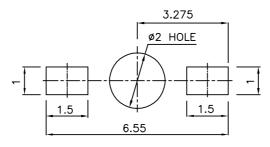


#### NOTES:

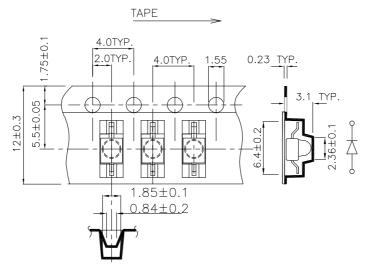
- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

## Recommended Soldering Pattern

(Units: mm)



## Tape Specifications (Units: mm)



#### Remarks:

If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:

- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2.Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

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